

**In the Claims:**

Please amend the claims as follows:

11. (AMENDED) A method for removing adhesive coatings from a plurality of substrates having dense submicron topography containing prominent sidewalls, comprising the steps of:

placing a quartz gas distribution plate, connected to a pressure regulated gas supply, in a tank containing a liquid chemical; submerging and placing a substrate carrier, containing a plurality of substrates, on said quartz gas distribution plate so that said substrates are aligned and in a vertical position relative to said quartz gas distribution plate;

said quartz distribution plate directs gas bubbles between and parallel to each surface of said substrates aligned thereabove, said gas bubbles providing a chemical-mechanical scrubbing;

removing said substrate carrier from said chemical liquid.

14. (AMENDED) The method according to claim 11 wherein using a quartz gas distribution plate is compatible with aggressive chemicals for removing adhesive residues in metal sidewalls that are coated with polymer.

15. (AMENDED) A method for stripping adhesive photoresist from a plurality of semiconductor wafers having dense submicron topography containing prominent sidewalls, comprising the steps of:

horizontally placing a quartz gas distribution plate, connected to a pressure regulated nitrogen supply, in an open tank containing a photoresist stripping chemical;

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- 35 submerging and placing a wafer cassette containing a plurality of wafers on said quartz gas distribution plate so that said wafers are aligned and in a vertical position relative to said quartz gas distribution plate;
- said distribution plate directs nitrogen bubbles between and parallel to each surface of said wafers aligned thereabove, said nitrogen bubbles providing a chemical-mechanical scrubbing;
- removing said wafer cassette from said photoresist stripping liquid.

16. (AMENDED) The method according to claim 15 wherein said quartz gas distribution plate having gas distribution means for generating an array of nitrogen bubbles, each row of said array corresponding to a wafer position contained in said wafer cassette.

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18. (AMENDED) The method according to claim 15 wherein using a quartz gas distribution plate is compatible with aggressive chemicals for removing adhesive residues in metal sidewalls that are coated with adhesive photoresist.